


Durafuse[®] LT



Versatile Solution for Your Process Challenges

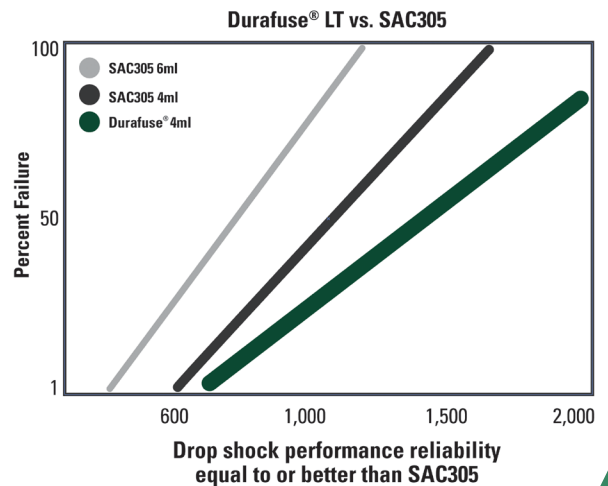
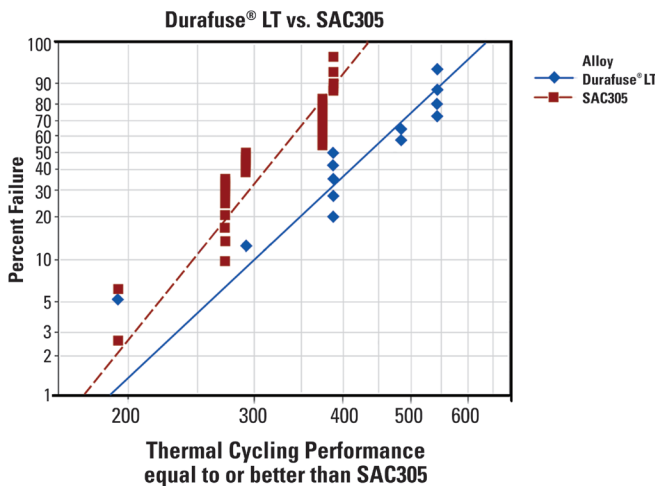
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Achieve high reliability while **reducing energy consumption by 10–15%**, compared to SAC305
- 

Enable **complex processes and designs**, such as step soldering, large temperature gradients, large BGA warpage, and fine feature printing
- 

The only low-temperature solder providing **excellent drop shock reliability**
- 

Superior thermal cycling performance on next generation component technology



indium.com/durafuse



Contact our engineer: cnash@indium.com

From One Engineer To Another[®]

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

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Form No. 100070 R2



Durafuse[®] HR



High-Reliability Alloy Solution

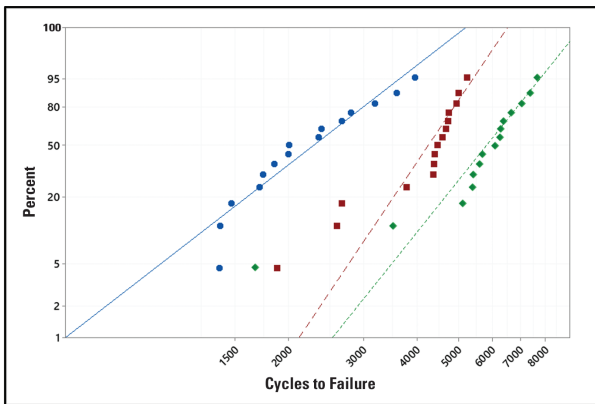
Enhanced thermal cycling reliability with low-voiding performance



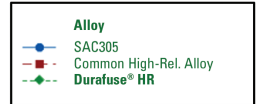
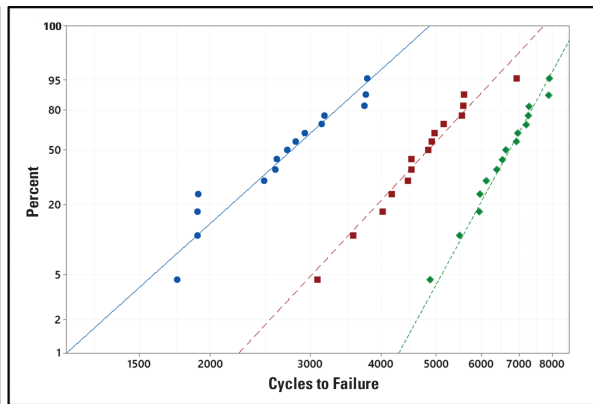
-40/+125°C thermal cycling conditions for 8,000+ cycles

- Reduced solder joint cracking
- Increased shear strength over time
- Longer characteristic lifetime (>3,000 cycles)

-40/125°C – BGA192 – ImSn Surface Finish



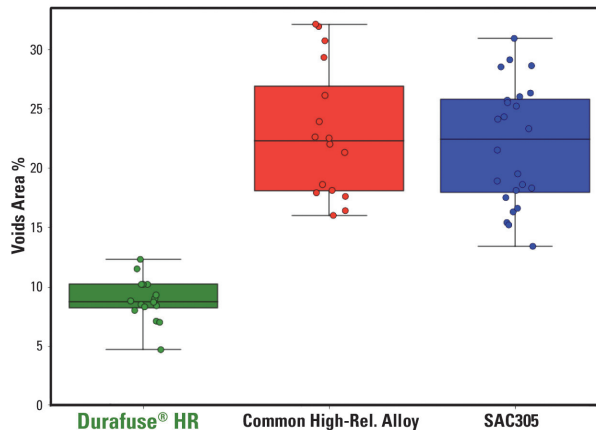
-40/125°C – QFN – ImSn Surface Finish



Superior voiding performance

- BGA, CSP, QFN and other bottom terminated components
- Common Surface Finishes

QFN on ImSn Surface Finish



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